100% Material Declaration Data Sheet SO8

Average Weight: 0.081174 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.00396**	**4.88%**
	Silicon	7440-21-3	100.00		0.00396	
Die Attach Material					**0.00124**	**1.53%**
	Epoxy resin(EP)	19690-82-2	21.00		0.0002604	
	Silver	7440-22-4	70.00		0.000868	
	Misc.		9.0	(Metal oxide, amine, gamma butyrolactone)	0.0001116	
Mold Compound					**0.041768**	**51.45%**
	Resin	Trade secret	7.50		0.003132	
	SiO2 Filler	60676-86-0	86.00		0.035921	
	Carbon Black	1333-86-4	0.50		0.000209	
	Epoxy Cresol Novolac	Trade secret	2.00		0.000835	
	Phenol Resin	Trade secret	4.00		0.001671	
Leadframe					**0.031948**	**39.36%**
	Copper	7440-50-8	97.50		0.031184	
	Iron	7439-89-6	2.35		0.000752	
	Phosphorus	7723-14-0	0.03		0.000009	
	Zinc	7440-66-6	0.12		0.000003	
Leadframe Plating					**0.000559**	**0.69%**
	Silver	7440-22-4	100.00		0.000559	
Bond Wire					**0.000223**	**0.27%**
	Gold	7440-57-5	100.00		0.000223	
Ext. Plating					**0.001476**	**1.82%**
	Tin	7440-31-5	85.00		0.001254	
	Lead	7439-92-1	15.00		0.000221	

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Xilinx believes this environmental information to be correct, but cannot guarantee its completeness or accuracy as it is based on data received from sources outside our company.

Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
8/15/07	1.0	Initial release.